

# PERFREZ® XT (CZ70CK49) Product Data Sheet

## Semiconductor applications

Our range of PERFREZ® high performance materials for semiconductor processes meets the most challenging and demanding applications for aggressive chemicals, gas and high temperatures. These materials offer excellent chemical and thermal resistance, thermal stability and high purity under these extreme process conditions.

We provide our customers with the highest quality products and technical support on seal design, material recommendation, installation techniques and test analysis, specifically for the semiconductor market.

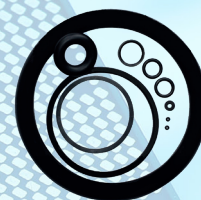
CZ70CK49 FFKM is a high temperature resilient perfluoroelastomer.

CZ70CK49 is specially designed for abatement, SubFab and Fab applications which require a broad range of chemical compatibility and excellent mechanical properties.

**Basic Polymer: Perfluoroelastomer**  
**Hardness: 70 +/- 5 Shore A**  
**Temperature range: -20°C to +240°C**  
**Colour: Black**

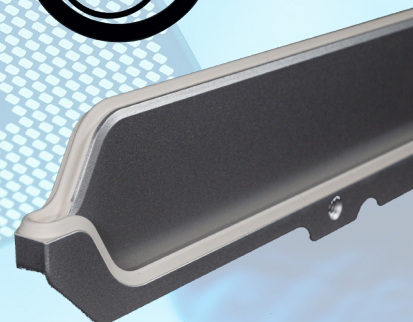
### Key features

- Superior physical properties with low CTE value
- Excellent oxygen and fluorine compatibility
- Low particle generation
- Low out-gassing



### Products

- High performance o-rings
- Special mouldings
- Rubber to metal moulding



Property	Results
Hardness (Shore A)	70 (+/- 5)
Elongation at break, %	106
Tensile Strength, psi (MPa)	1196 (8.25)
Modulus @ 100%, psi (MPa)	1049 (7.23)
Min. Operating Temperature, °C (°F)	-20 (-4)
Max. Operating Temperature, °C (°F)	240 (464)
Compression Set @ 200°C, %	21.5

### Applications

- KF-Fittings
- Isolator Valve Seals
- Bell Jar Seals
- Door Seals
- End Point Windows
- Gas Inlet Valves
- Slit Valves
- Window Seals

These results represent typical material properties and are not to be used for specification purposes. They are achieved under laboratory conditions and do not necessarily correspond to results measured on finished goods. It does not absolve the customer of the responsibility to make tests for their intended process or purpose. Ceetak Ltd makes no warranties and assumes no liability in connection with any use of this information.